



DATA SHEET

CHIP Low Impedance 105°C

Serie: I15008

Voltage:	16Volt	Range:	1000μF
Impedance:	0,15Ω	Dimension	10x10,5mm
Ripple Current:	670mA		

CHIP Low Impedance 105°C
Serie No.: I15008
Customer:

DRW:	Jason	CHKD	Wilson	MATL:	Wilson	TOLERANCE	Mason	DATE	03.06.2014
APPD:	Schumi			FINISH	Jamy			Sheet No.	1 from 7

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Designed for surface mounting on high density circuit board

Emboss carrier tape packing systems is available for automatic insertion



Technical Informations

Voltage:	16Volt
Range;	1000µF
Dimension; D x L mm	10x10,5mm
Impedance (Ω) max., at20°C, 100hKz	0,15Ω
Ripple Current (mA rms) at 105°C, 100kHz	670mA

Ordering Code			
160	Voltage		
102	Range		
D=	G	L=	4

Low Impedance with Operating Temperatur Range of -55°C ~ +105°C
Load Life of 1000~2000hours

Leakage current max.	Ø4 ~ Ø10mm	I= 0,01CV or 3µA whichever is greater (after 2 minutes)
	Ø12,5 ~ Ø16mm	I= 0,03CV or 4µA whichever is greater (after 1 minutes)

Capacitance tolerance ± 20% at 120Hz, 20°C

Dissipation factor max. (at 120Hz, 20°C)	WV		6,3	10	16	25	35	50								
	Tanδ	Ø4 ~ Ø10mm	0,22	0,19	0,16	0,14	0,12	0,12								
		Ø12,5 ~ Ø16mm	0,26	0,22	0,18	0,16	0,14	0,12								

Low Temperatur characteristics (Impedance ratio at 120Hz)	WV		6,3	10	16	25	35	50								
	Ø4 ~ Ø10mm	Z-25°C / Z+20°C	2	2	2	2	2	2								
		Z-55°C / Z+20°C	5	4	4	3	3	3								
	Ø12,5 ~ Ø16mm	Z-25°C / Z+20°C	3	3	2	2	2	2								
Z-55°C / Z+20°C		10	8	6	4	3	3									

Load Life (after application of the rated voltage for 2000hrs at 105°C	Leakage current	Less than specified value
	Capacitance Change	Within ±20% of initial value
	Tanδ	Less than 200% of specified value
	Ø4 ~ Ø6,3x5,4: 1000hours	

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Shell life (at 105°C) After 1000hours no load test, leakage current, capacitance and tan δ are same as load life value.

Resistance to soldering heat	After reflow soldering and resistance at room temperature, they meet the characteristics requirements listed at underside	
	Leakage current	Less than specified value
	Capacitance Change	Within \pm 10% of initial value
	Tan δ	Less than specified value

Size	FREQUENCY COEFFICIENT OF PERMISSIBLE RIPPLE CURRENT					
	Capacitance μ F	Frequency				
		50Hz	120Hz	300Hz	1KHz	10KHz \leq
\varnothing 4 ~ \varnothing 10mm	1,0~ 68	0,35	0,50	0,64	0,83	1,00
	100~2200	0,40	0,55	0,70	0,85	1,00
\varnothing 12,5 ~ \varnothing 16mm	~680	0,45	0,65	0,80	0,90	1,00
	1000 ~4700	0,65	0,85	0,95	1,00	1,00

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Technical Drawing

Dimension of Size \varnothing 8x10,5 ~ 16mm



Dimension of Size \varnothing 4~ 8x6,2mm



D x L	\varnothing 4 x 5,4	\varnothing 5 x 5,4	\varnothing 6,3 x 5,4	\varnothing 6,3 x 7,7	\varnothing 8 x 6,2	\varnothing 8 x 10,5	\varnothing 10 x 10,5	\varnothing 10 x 13,5	\varnothing 12,5 x 13,5	\varnothing 12,5 x 16	\varnothing 16 x 16,5
A	2,0	2,2	2,6	2,6	3,4	3,0	3,3	3,3	4,9	4,9	5,8
B	4,3	5,3	6,6	6,6	8,4	8,4	10,4	10,4	13,0	13,0	17,0
C	4,3	5,3	6,6	6,6	8,4	8,4	10,4	10,4	13,0	13,0	17,0
E +/-0.2	1,0	1,3	1,9	1,9	2,3	3,1	4,7	4,7	4,7	4,7	6,4
L	5,4	5,4	5,4	7,7	6,2	10,5	10,5	13,5	13,5	16,0	16,5

*1 Voltage mark (6V) represents 6,3V for \varnothing 4 ~ 10mm

*3 (L +/- 0.5) is applicable to \varnothing 8x10,5 ~ \varnothing 10mm

*2 (L +/- 0.3) is applicable to \varnothing 6,3 ~ 7.7 and \varnothing 8 + 6,2mm

*4 (L +/- 1.0) is applicable to \varnothing 12,5 ~ \varnothing 16mm

RE. Date code and seriew type -1st digit for Year 2nd digit for Quarter, 4 quarter codes in one year area 1,4,7,0

3rd character for Serie S

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Voltage Ordering Code	Code
4,0	4V0
6,3	6V3
10	100
16	160
25	250
35	350
50	500
63	630
80	800
100	101

Diameter ordering Code D	Code
3mm	3
4mm	A
5mm	B
6,3mm	C
8mm	E
10mm	G
12,5mm	I
16mm	K

Height ordering Code L	Code
4mm	A
5,4mm	0
5,8mm	1
6,2mm	2
7,7mm	3
10,5mm	4
13,5mm	5
16mm	6
16,5mm	7

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Ordering Informations

Serie	Voltage Code	Tolerance Code	Range Code	Size Code D	Size Code L	Special function	ROHS	Packing Code		
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I15008	160	M	102	G	4	XX	R	TR		
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look table Voltage Code	M= ±20%	Ordering Code Range	Look table Code D	Look table Code L	XX= No function	R= ROHS Conform N= NON ROHS Conform	TR= Tape Reel Packing BU= Bulk-Ware		
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Soldering Profile Curve

Classification Reflow Profile (JEDEC J-STD-020C)



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